GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
RAJYA SABHA
UNSTARRED QUESTION NO. 1506
TO BE ANSWERED ON: 12.12.2025

INDIGENOUS MANUFACTURE OF DATA CENTRE EQUIPMENT

1506. **SHRI KESRIDEVSINH JHALA:**
      DR. ANIL SUKHDEORAO BONDE:

Will the Minister of Electronics and Information Technology be pleased to state:

(a) whether Government is taking any initiative to develop indigenous manufacturing capacity for data center equipment;
(b) if so, the incentives being provided to encourage domestic manufacturing of servers, storage devices and network infrastructure to reduce import dependency;
(c) whether supply chain vulnerabilities have been identified for lack of domestic water cooling systems, power management equipment; and
(d) if so, whether these issues are being addressed through dedicated policy interventions;
(e) if so, the details thereof; and
(f) the estimated timeline for achieving 'Make in India' components in 30-40 per cent of operational data centers by 2030?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI JITIN PRASADA)

(a) to (f): Data centres rely on a wide range of equipment, including computer hardware, telecom systems, and mechanical, electrical and cooling infrastructure. The Government of India's electronics and semiconductor policies are guided by the Hon'ble Prime Minister's vision of *Aatma Nirbhar Bharat* and *Make in India*.

The global electronics manufacturing supply chain involves multiple countries and companies. India's policy approach is to progressively develop the domestic manufacturing supply chain for data-centre equipment and components.

As part of this strategy, the ecosystem in India is expanding rapidly through initiatives such as the Electronics Components Manufacturing Scheme (ECMS), Semicon India Programme, PLI for Large Scale Electronics Manufacturing, PLI for IT Hardware, SPECS, and Electronics Manufacturing Clusters (EMC/ EMC 2.0).

The relevant polices of government of India to promote the manufacturing of data-centre devices, equipments and components are as follows:

PLI Scheme for IT Hardware
The scheme promotes the domestic production of Servers, Laptops, Tablets, All-in-One (AIO) PCs and Ultra Small Form Factor (USFF) devices.

Electronics Components Manufacturing Scheme (ECMS)
ECMS covers optical transceivers and passive components used in servers, routers and networking systems. The Government has received encouraging response from the industry for manufacturing these.

PLI for Telecom & Networking Products
PLI scheme for telecom equipment, incentivising the local production of routers, switches and other networking gear, which form an essential part of data-centre and server infrastructure

To further strengthen the supply-chain security and transparency, CERT-In issued technical BOM guidelines in July 2025 for software, hardware, AI, quantum and cryptography components.

Design Linked Incentive (DLI)
To leverage India's strength in chip design, Government has launched DLI Scheme. Support has been provided for 24 chips and System on Chips (SoCs) for satellite communication, drones, surveillance cameras, Internet of Things (IoT) devices, LEDs driver, AI devices, telecom equipment, smart metres, etc.

National Supercomputing Mission (NSM)
Under NSM, CDAC has designed and developed indigenous server "Rudra". This Rudra server has been customised by the industry partners for meeting the data center server requirements.
Further MeitY has notified Server under Public Procurement (Preference to Make in India) Order (PPO) to aggregate government demand and to increase domestic value addition vide notification dated 12.10.2023.

****